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PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application : Wushing Yin, et al.
Application No. : 10/636,105
Filed : August 7, 2003
Confirmation No. : 9143
For : INTEGRATED UNDERFILL PROCESS FOR BUMPED
CHIP ASSEMBLY
Examiner : Donghai D. Nguyen
Attorney's Docket : INDUM-110XX

TC Art Unit: 3729

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I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on 7-29-05.

By: *Victor B. Lebovici*

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STATUS LETTER

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

Further to the filing of the above-identified application on August 7, 2003, information is requested as to the present status of the above-identified application.

Respectfully submitted,

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